

반도체의 P-N 접합과 Scanning Photo Current Microscopy

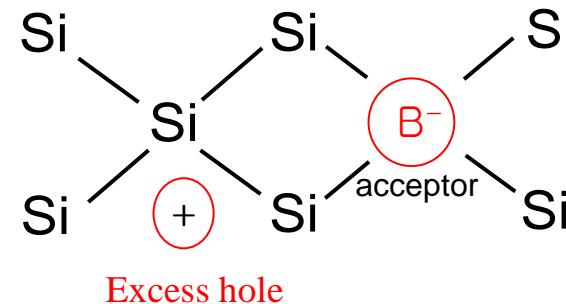
세종대학교
서용호

도핑에 의한 반도체의 전기전도도 증가

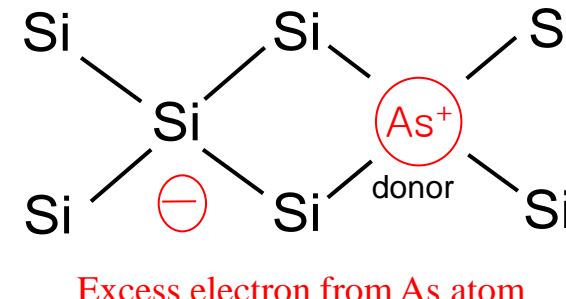
Conductivity of Semiconductor by doping

- 불순물 Impurities (or doping) of semiconductor
→ affect the electrical, optical, and magnetic properties
- 도핑 doping ($10^5 : 1$, ~10 ppm) increases conductivity by factor of 10^3 (at R.T.)

- Acceptor(3족 원소) : (p-type)
 Si, Ge + B
(IV) (III)

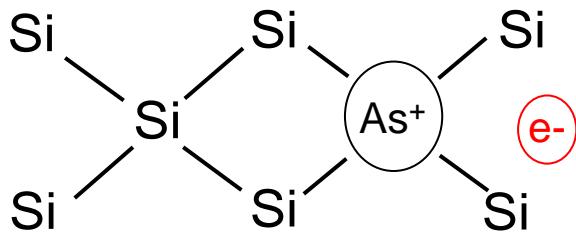


- Donor (5족 원소) : n-type
 Si, Ge + P, As, Sb
(IV) (V) (arsenic) (antimony)

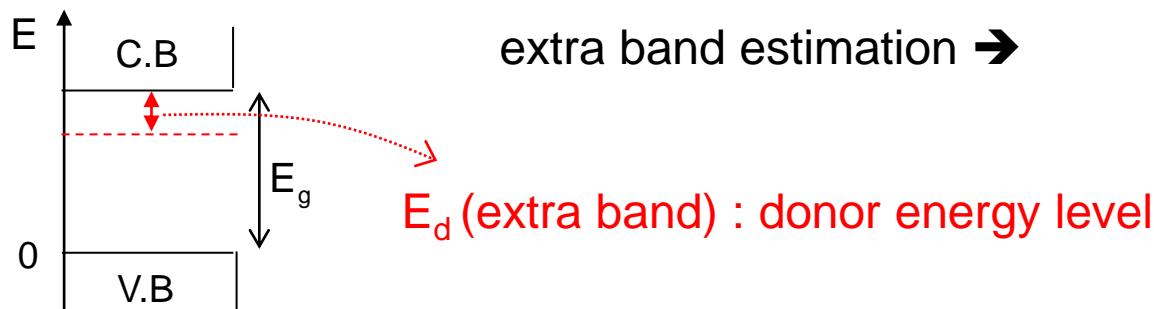


Donor(도너) state

- Donor state: 전도대 근처에서 임여전자가 유도됨
 - Donor electrons move under Coulomb potential $\frac{e}{\epsilon r}$ between charges in the medium (ϵ : static dielectric constant)
- Energy level of extra electron is modified by donor



- 임여전자와 3족 이온간의 쿨롱에너지가 추가되어 유전율 ϵ 의 실리콘 결정내에서 에너지 밴드 구조에 에너지 대역이 추가됨.



Donor energy level

<보어의 수소원자 모형>
(Bohr hydrogen model)

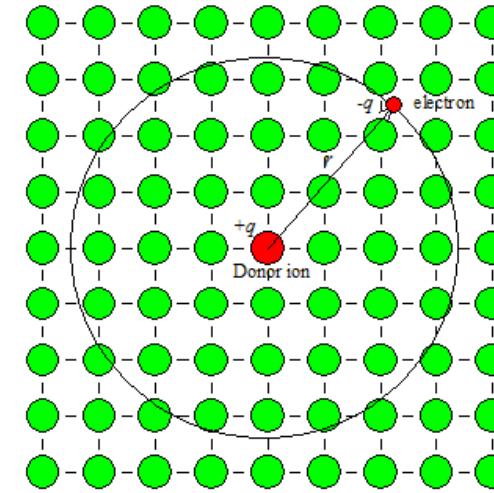
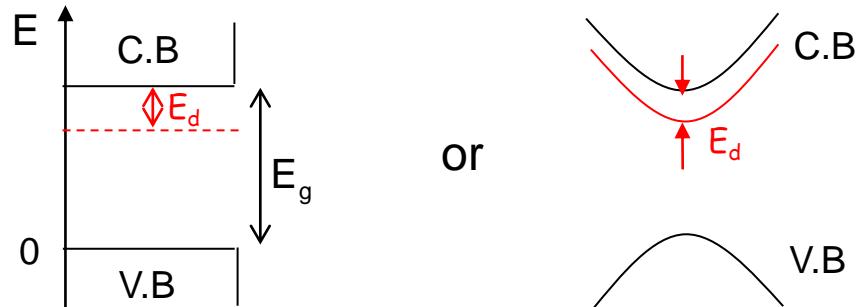
$$-\frac{e^4 m}{2\hbar^2} = -13.6 \text{ eV}$$

수소원자의 이온화 에너지
ionization energy of hydrogen

- Extra electron from donor contributes to conduction, as it is ionized
- **Donor energy level ($\equiv E_d$)** : ionization energy of extra electron in dielectric medium (ϵ) (Si lattice)
- from Bohr model $e^2 \rightarrow e^2/\epsilon$; $m \rightarrow m_e$ (effective mass of el.)

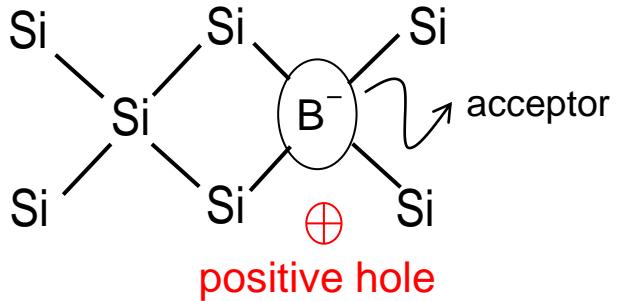
$$\therefore E_d = \frac{e^4 m_e}{2\epsilon^2 \hbar^2} = \left(\frac{13.6 m_e}{\epsilon^2 m} \right) \text{eV} \approx 30 \text{ meV}$$

도너의 이온화 에너지

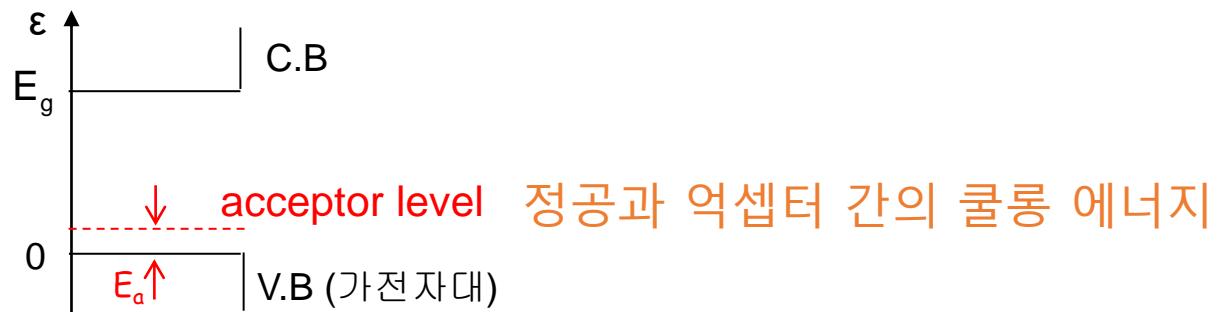


Acceptor(억셉터) States

- Host material : Group 4 (Si, Ge)
Impurity : group 3 (B, Al, Ga, In)



억셉터: 전자를 받아들일 수 있는 빈 자리 (정공)
"acceptor": accepts an electron in medium
induces a positive hole 정공



Acceptor ionization energy ($E_a = \frac{13.6}{\epsilon^2} \frac{m_h}{m}$) : (10~50 meV)

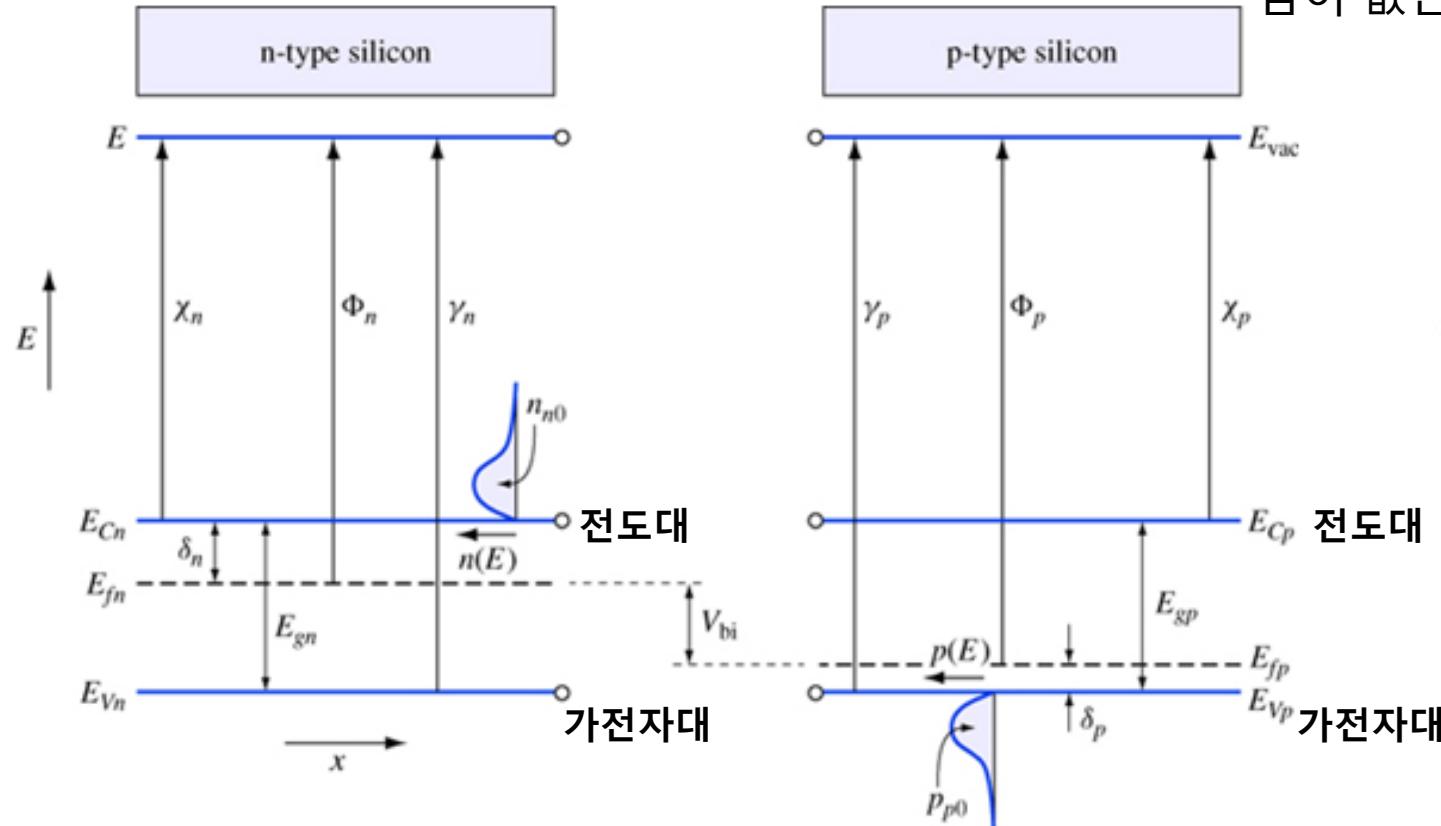
Si vs Ge ($\epsilon_{Si}=11.7$, $\epsilon_{Ge}=15.8$)

→ 상온에서 $k_B T = 1.38 \times 10^{-23} (J/K) \times (295K) \sim 26 \text{ meV}$

열적 이온화 "Thermally ionization" of donor or acceptor
→ important for the electrical conductivity

P-N junction band diagram

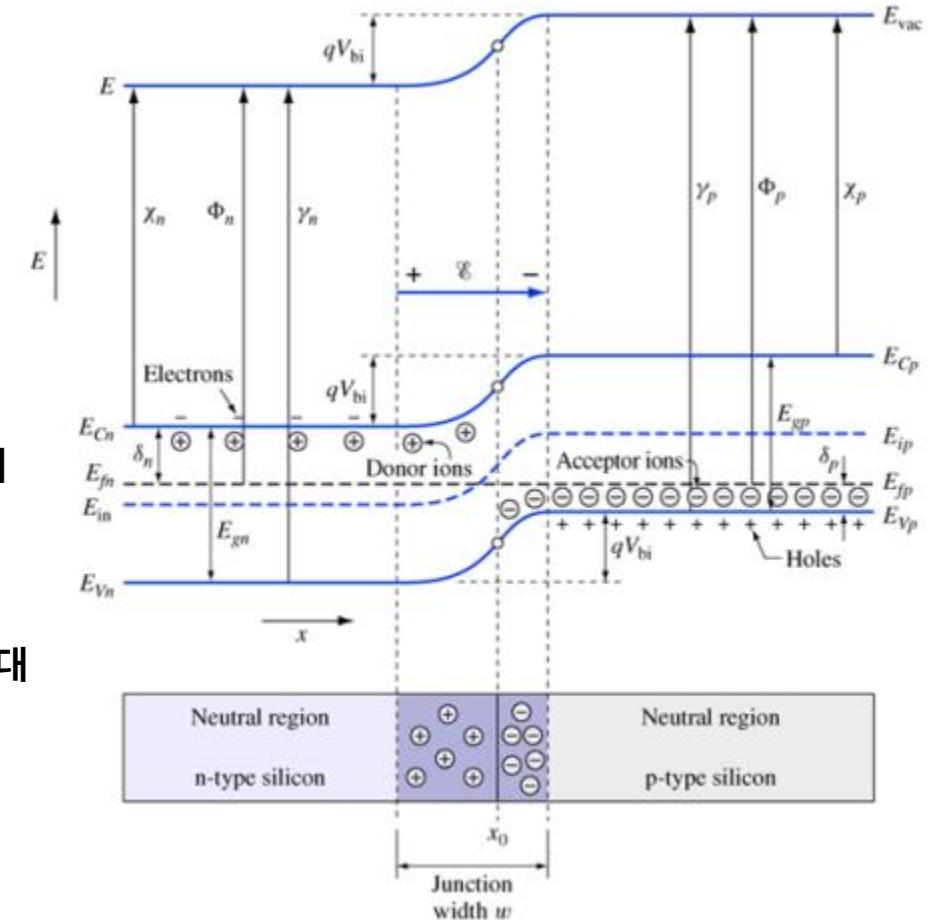
vacuum level(진공 준위)는 전자 또는 정공에 가해지는 힘이 없는 **자유로운 상태**에 해당하는 에너지 준위



χ (chi, 카이): 전자 친화도 electron affinity

γ : 이온화 에너지 ionization energy

Φ : work function



P-N junction Diode

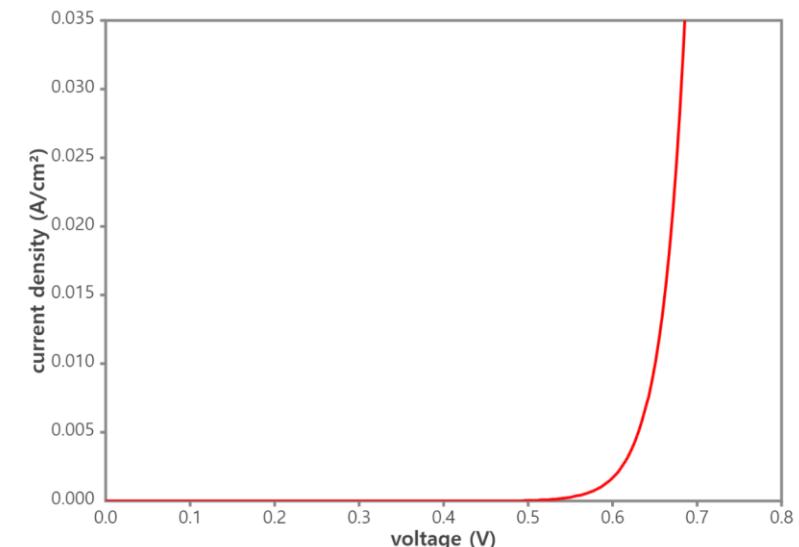
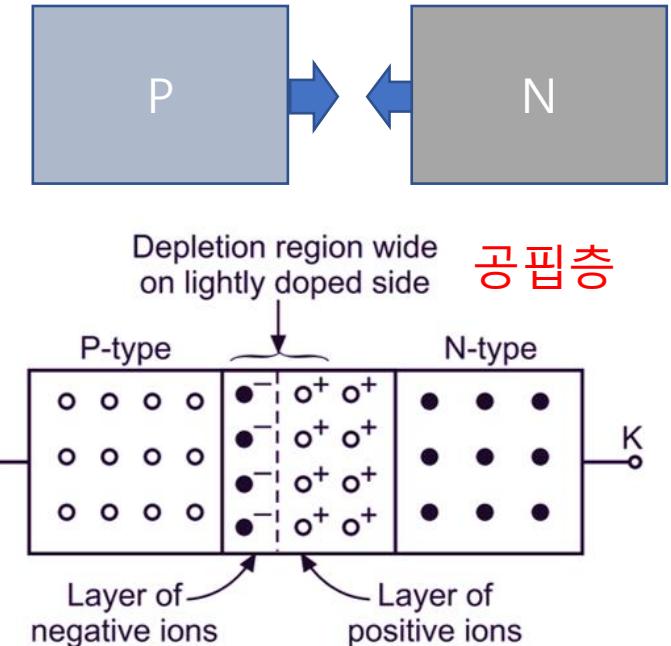
- P-N junction Diode Equation $I = I_0(e^{\frac{qV}{k_B T}} - 1)$
- I_0 : 역방향 포화전류 “reverse bias saturation current”,
the diode leakage current density in the absence of light;
진성 캐리어 농도의 제곱에 비례함 ($I_0 \propto n_i^2$)
- Diode Equation for Non-Ideal Diodes (비이상적인 다이오드)

$$I = I_0(e^{\frac{qV}{nk_B T}} - 1) \quad \frac{I}{I_0} + 1 = e^{\frac{qV}{nk_B T}}$$

n = ideality factor, a number between 1 and 2 which typically increases as the current decreases

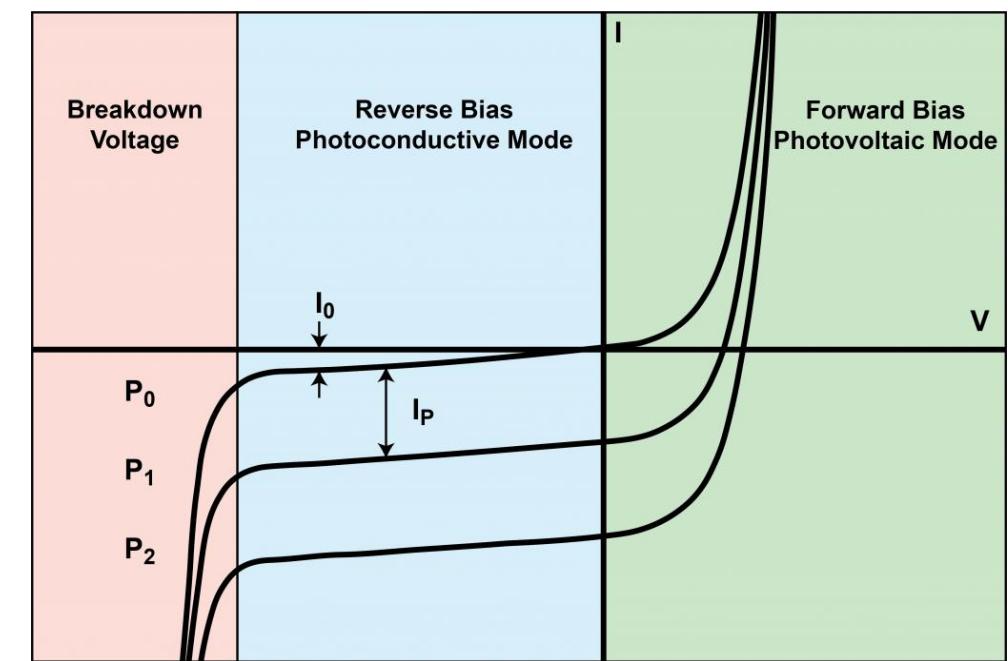
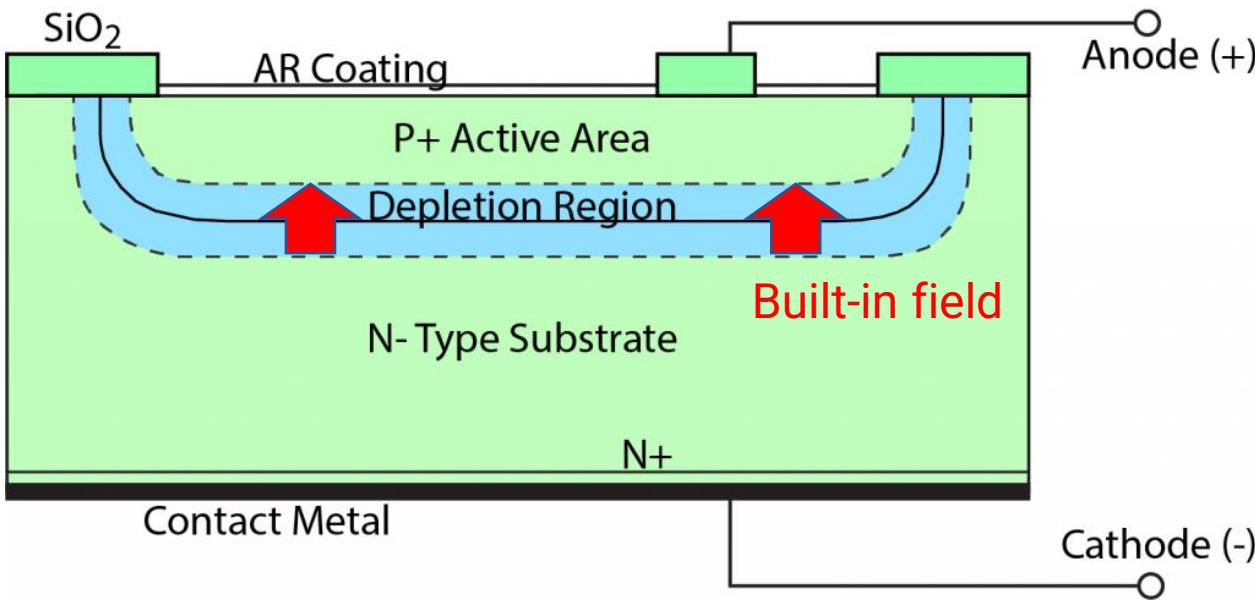
For forward bias, $I \gg I_0$

$$\frac{I}{I_0} \cong e^{\frac{qV}{nk_B T}}$$



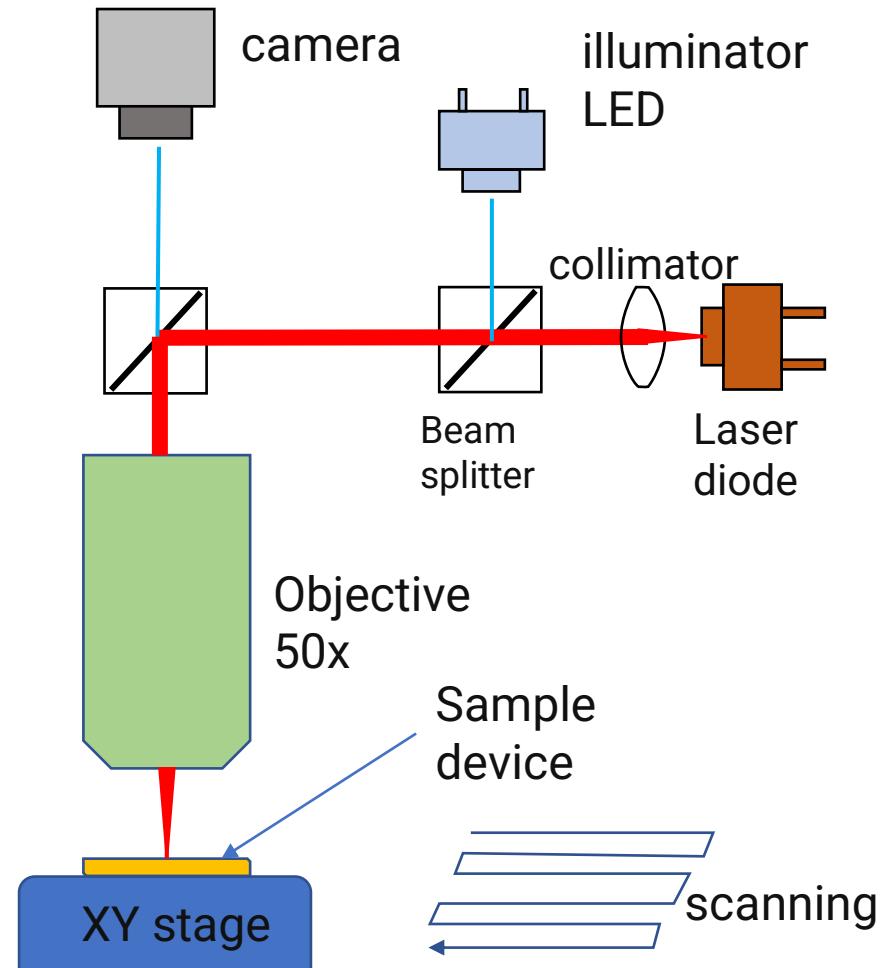
광전류 (photocurrent)

- 밴드갭 에너지 보다 높은 에너지의 광자(빛)이 반도체에 닿으면 전자-정공 쌍이 발생 → 바로 재결합
→ 열 발생
- 빛이 공핍층에 닿으면 Built-in 포텐셜에 의해서 서로 반대 방향으로 힘 → 전자-정공 분리 → 광전류



Scanning photocurrent imaging → local photoelectric effect in air

- 빛이 공핍층에 닿으면 전자-정공 쌍이 발생
- Built-in 포텐셜에 의해서 전자-정공 분리 → 광전류
- 광전효과 photoelectric effect : 진공에서 측정
- 실제 소자는 공기중에서 측정: photoelectric effect from pn junction measured by photocurrent mapping
- 용도(usage): 태양광소자, pn-junction 소자, LED, Image sensor, 등 다양한 광전소자 연구 개발
- 제조사(주)세종과학기기, 모델명:SPCM01

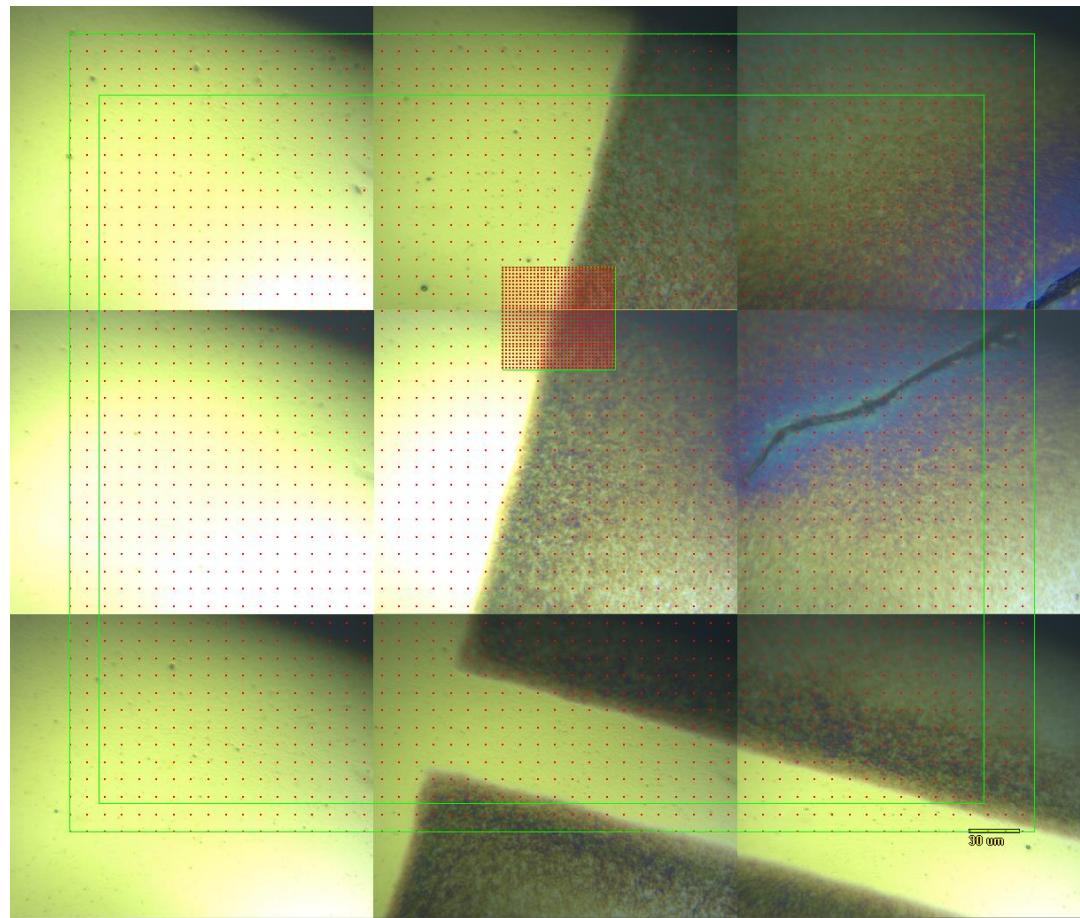
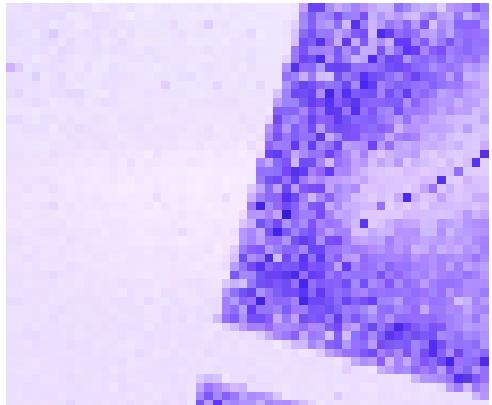


Photocurrent map and confocal image

Photocurrent



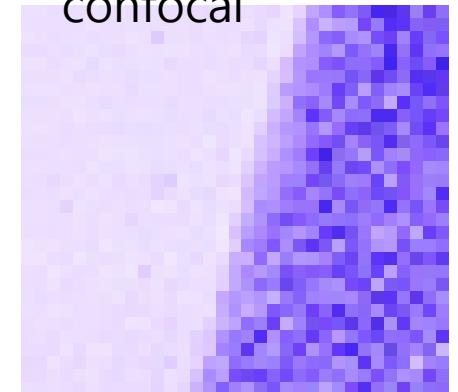
confocal



Photocurrent



confocal



Mxene-Si Solar Cell : fabrication process

Bare Si wafer cleaning

1. Acetone, Methanol, IPA, DI 15min (sonication)
2. BOE 5min / DI 5min 2times
3. DI washing many time

Bottom electrode deposition

- Ti / Pd / Ag : 50nm / 50nm / 90nm

Top coating

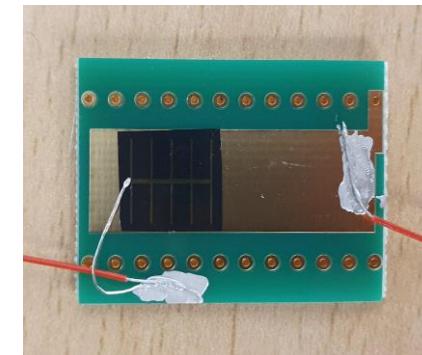
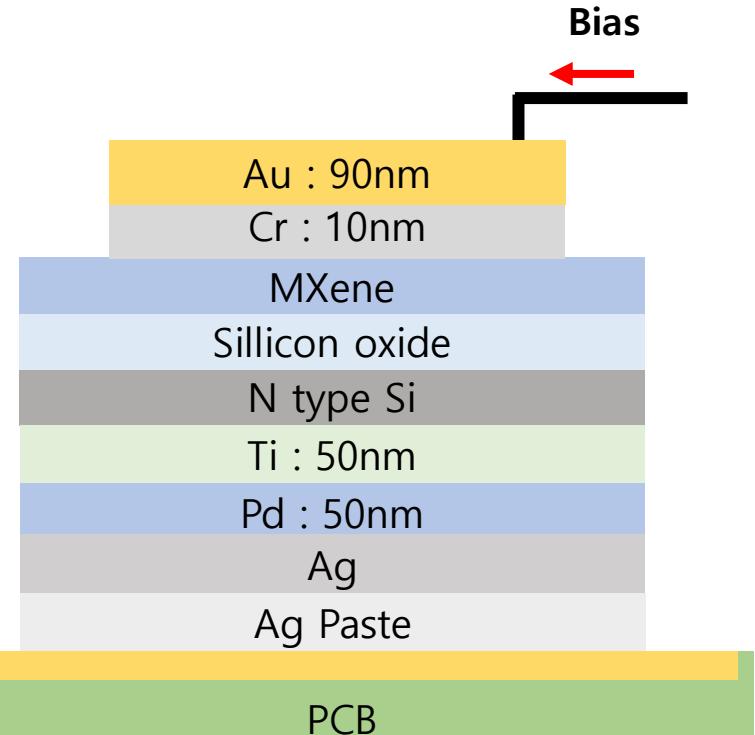
- BOE 5min / 상단 Si의 산화막 제거
- DI water(90°C)내에서 산화막 성장시킴 / 2hr
- UV 경화기 이용, 20분간 O₃ treatment
- Spin coating (1step : 500rpm, 10s / 2step : 2000rpm, 60s)
- Heating 100°C 10min

Annealing (tube furnace)

- At 300°C 1hr / Ar = 50 [sccm]

Top electrode deposition

- Cr / Au : 10nm / 90nm



MXene synthesis by Etching MAX

알미늄 식각

	Condition
MAX	Ti ₃ AlC ₂ 1g
Etchant	HCl 30ml + LiF 1.98g
Etching time	24hour
Temperature	70°C
Etch RPM	300 rpm

증화과정 (pH=7)

No	Centrifuge RPM	Time
1	3500rpm	5min
2	3500rpm	5min
3	3500rpm	5min

Mxene 층분리과정

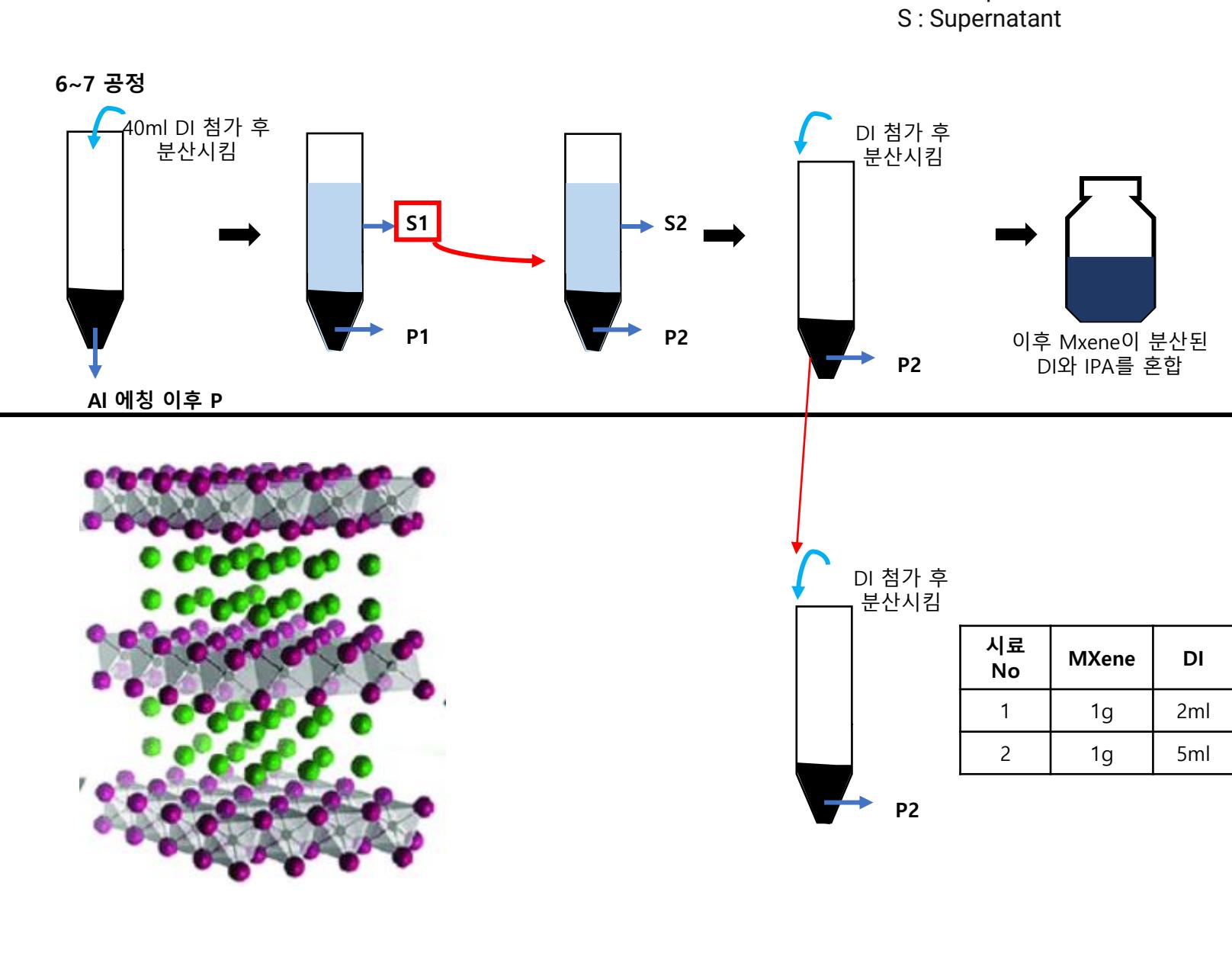
No	Process	Time
4	Sonication	1hr

식각 부산물 제거

No	Centrifuge RPM	Time
5	3500rpm	1hr

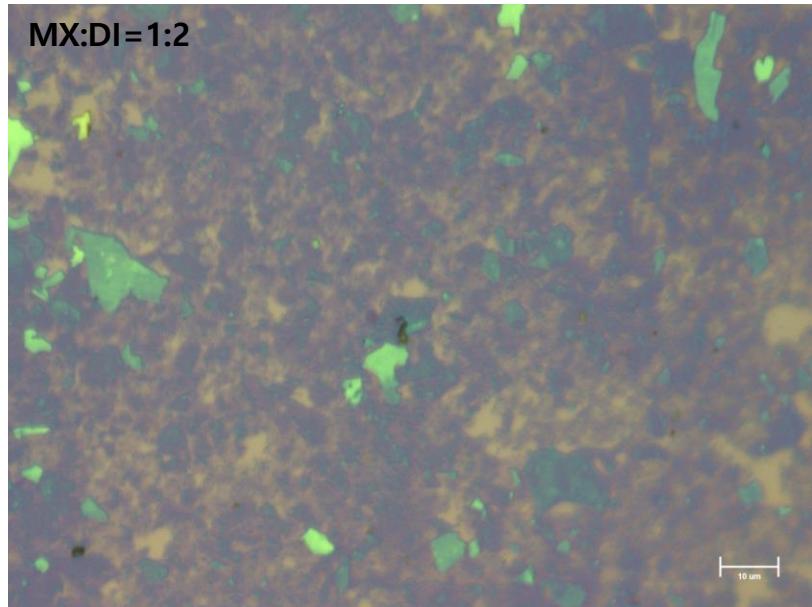
Mxene Solution 제작과정

No	Centrifuge RPM	Time
6	3500rpm	10min
7	10000rpm	10min

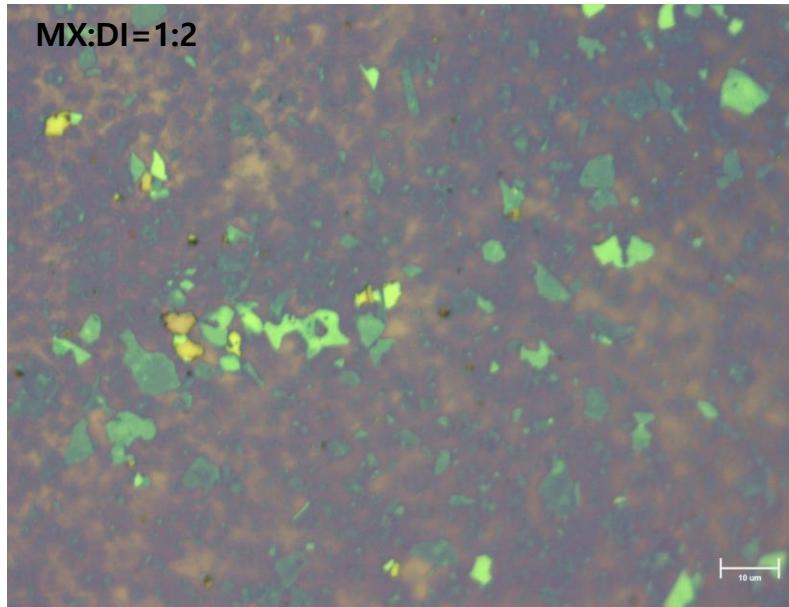


MXene deposition after sonication

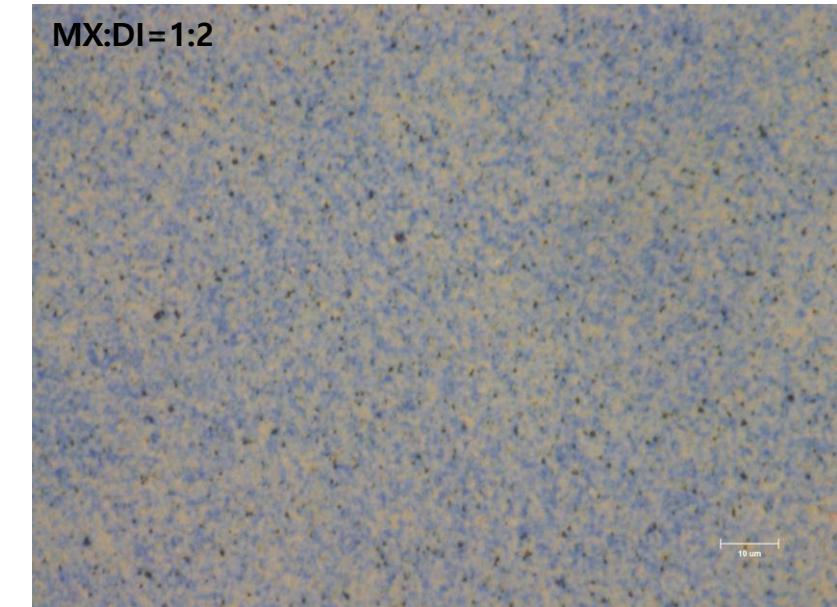
No Sonication



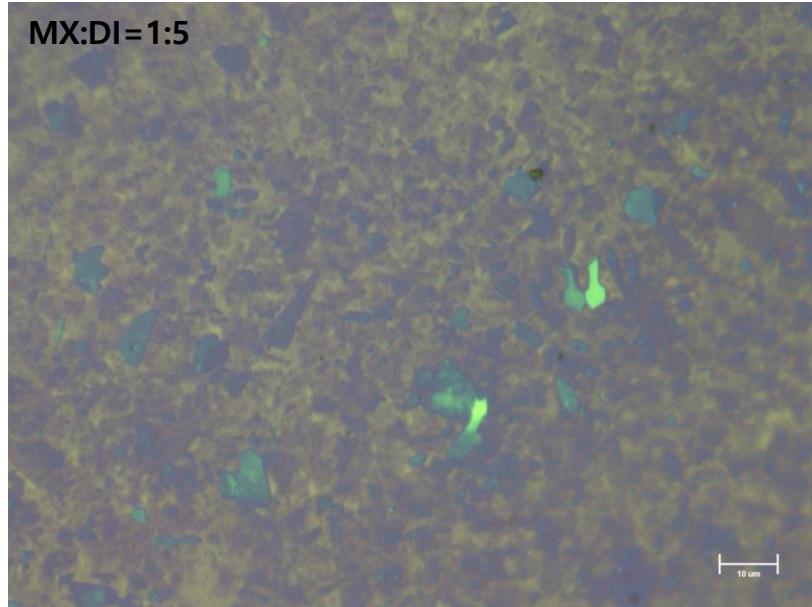
Sonication 30min



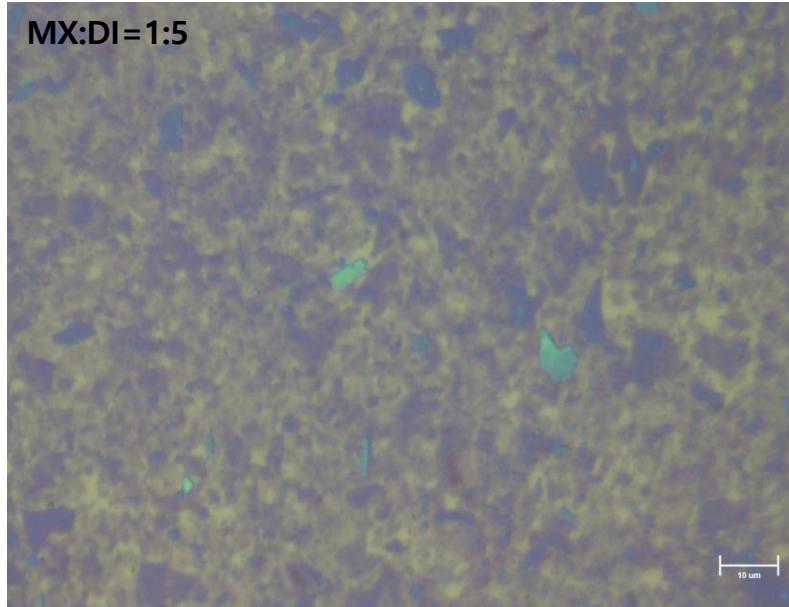
Sonication 1hr



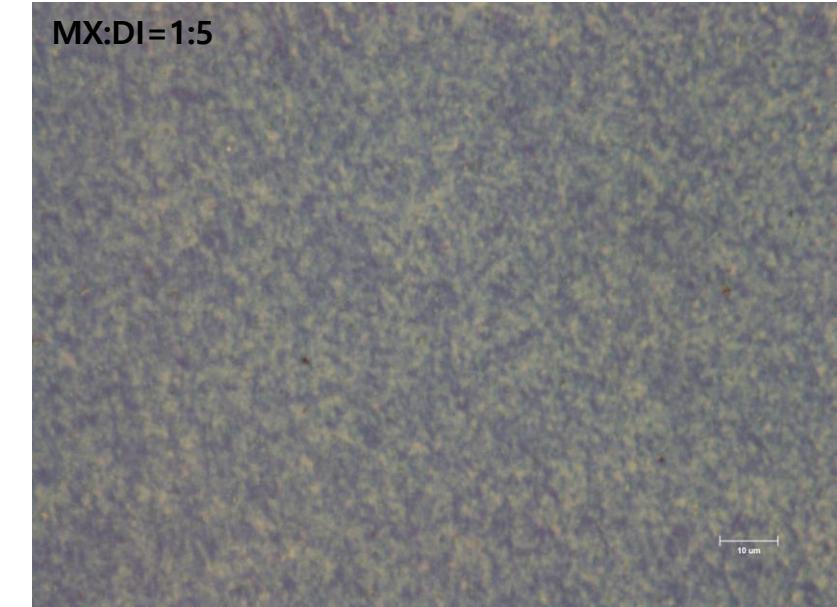
MX:DI=1:5



MX:DI=1:5



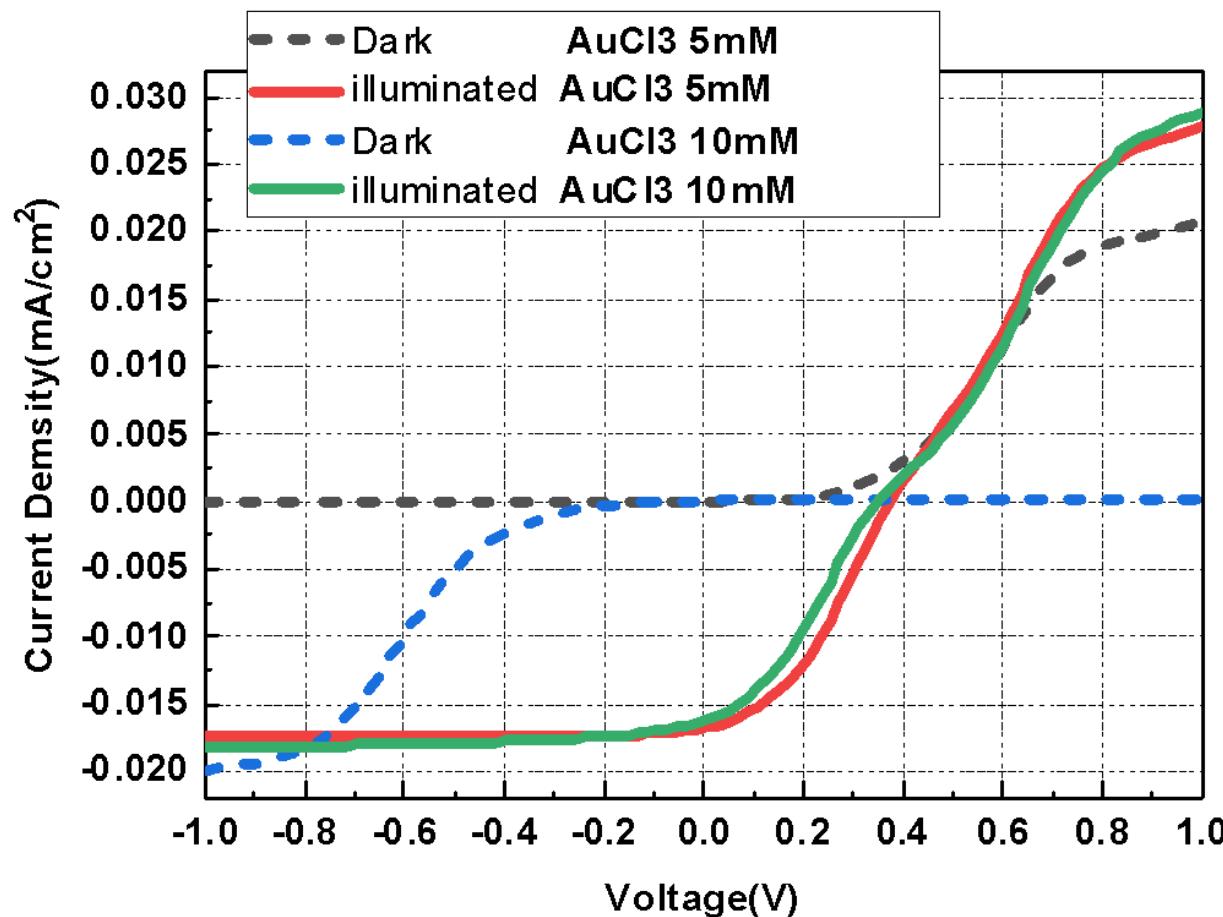
MX:DI=1:5



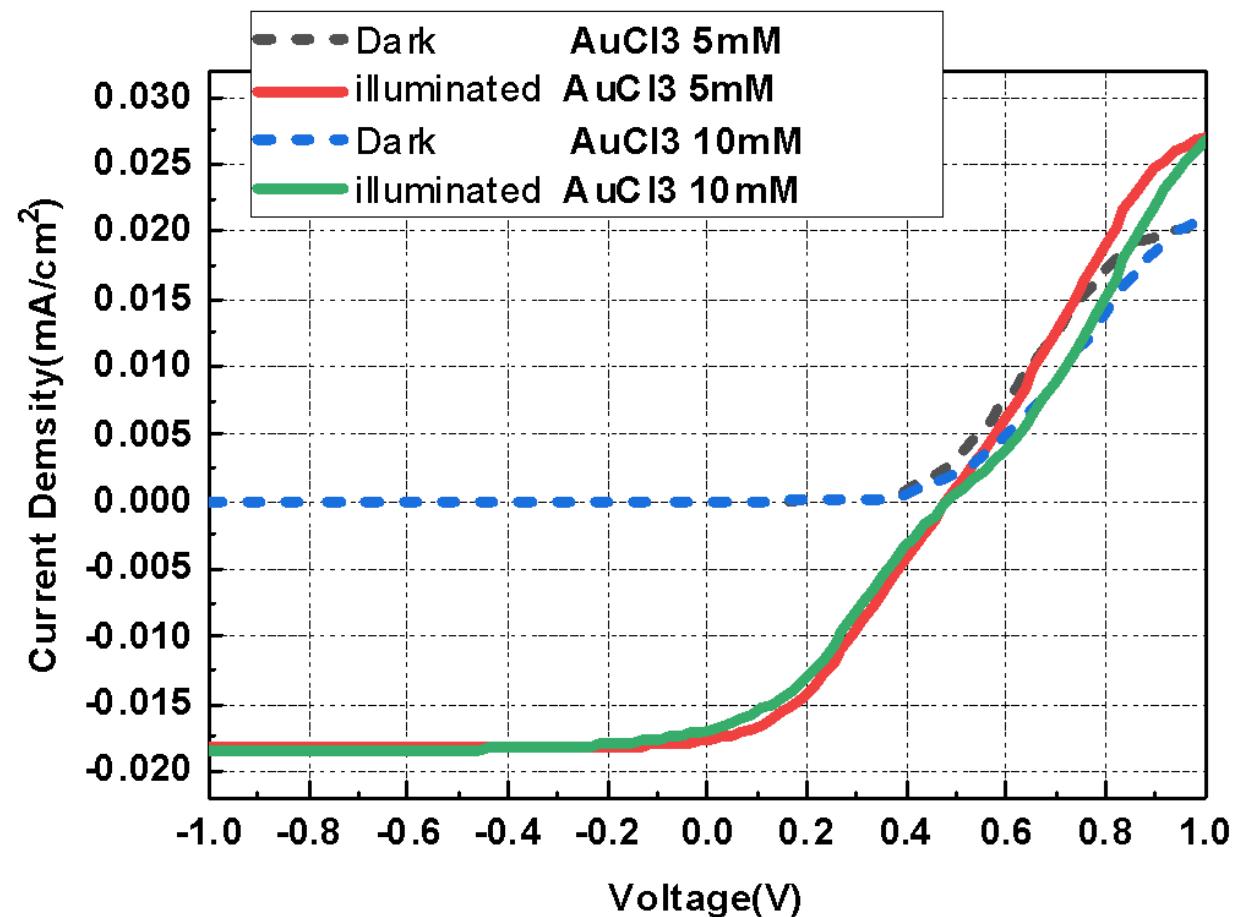
Solar cell measurement – 210708

MX in DI 6ml

$\text{Al}_2\text{O}_3 = 7\text{cycle} = \approx 9.8\text{\AA}$



$\text{Al}_2\text{O}_3 = 14\text{cycle} = \approx 19.6\text{\AA}$



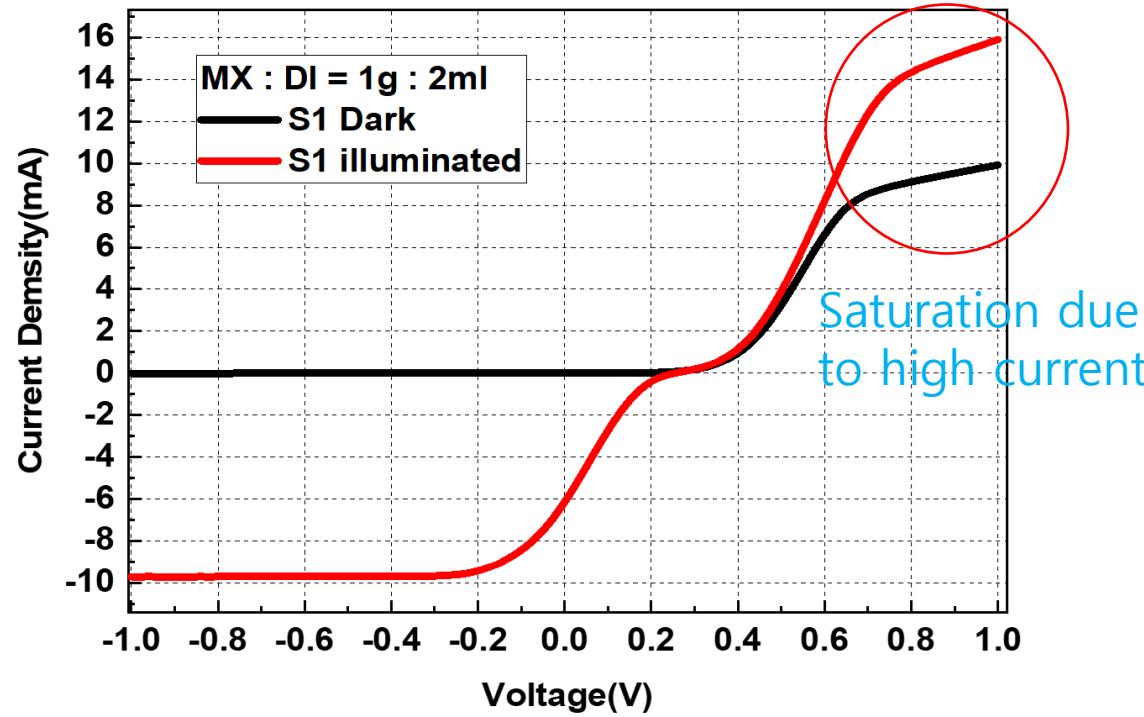
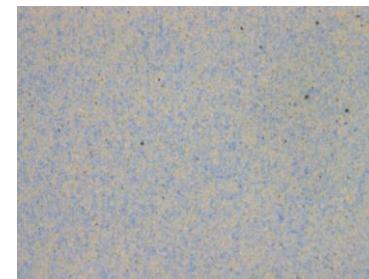
[MX in DI]	Al_2O_3	AuCl_3	Voc [V]	Isc [A]	$\text{Jsc [mA/cm}^2]$	FF	Efficiency
6ml	1nm	5mM	0.3755	0.0168	18.6519	38.4932	2.6964
6ml	1nm	10mM	0.3513	0.0164	18.2374	33.3097	2.1344

[MX in DI]	Al_2O_3	AuCl_3	Voc [V]	Isc [A]	$\text{Jsc [mA/cm}^2]$	FF	Efficiency
6ml	2nm	5mM	0.4819	0.0176	19.6004	35.6042	3.3628
6ml	2nm	10mM	0.4854	0.0171	19.0241	32.5176	3.0031

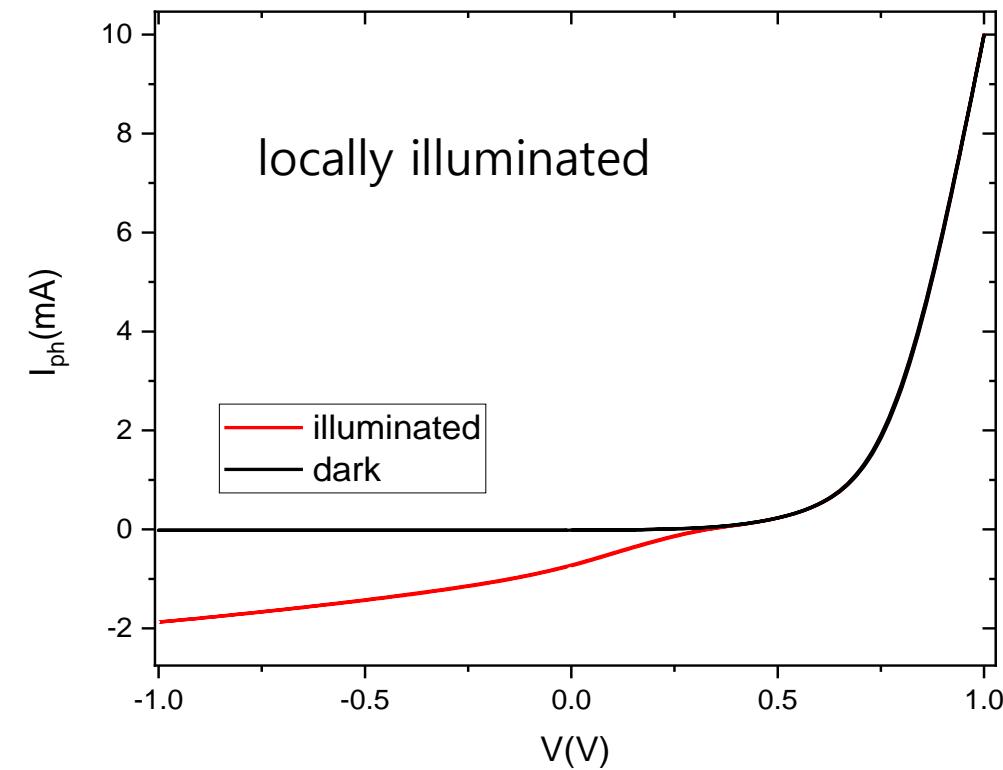
Solar simulator measurement

No.	SiO ₂ growth	[Mxene : DI]	Voc [V]	Isc [A]	Jsc [mA/cm ²]	FF	Efficiency
S1	2hr	[1 : 2]	0.2546	0.0061	6.8141	17.6482	0.3062
S2	2hr	[1 : 5]	0.2727	0.0121	13.4591	22.6547	0.8315

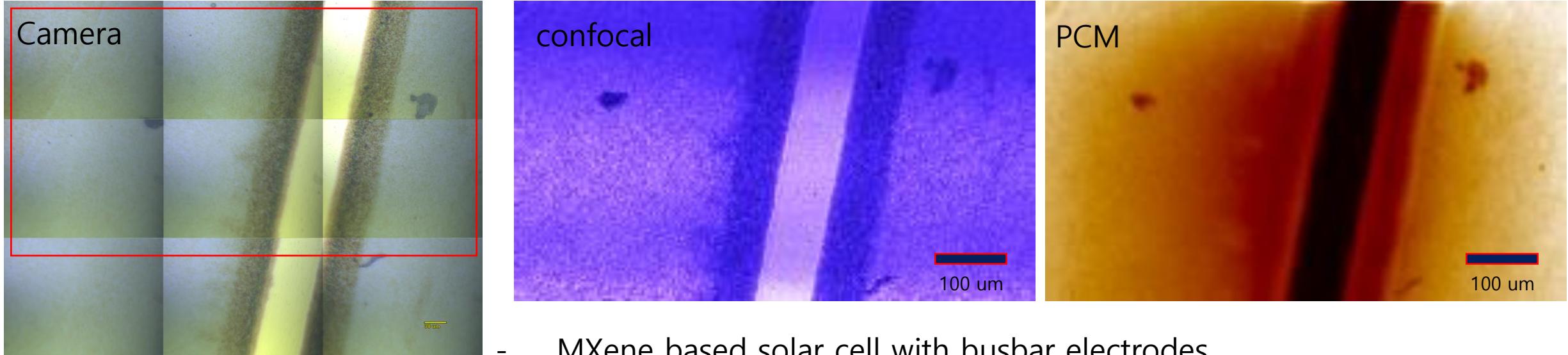
SN210521, MX:DI=1:2/1:5



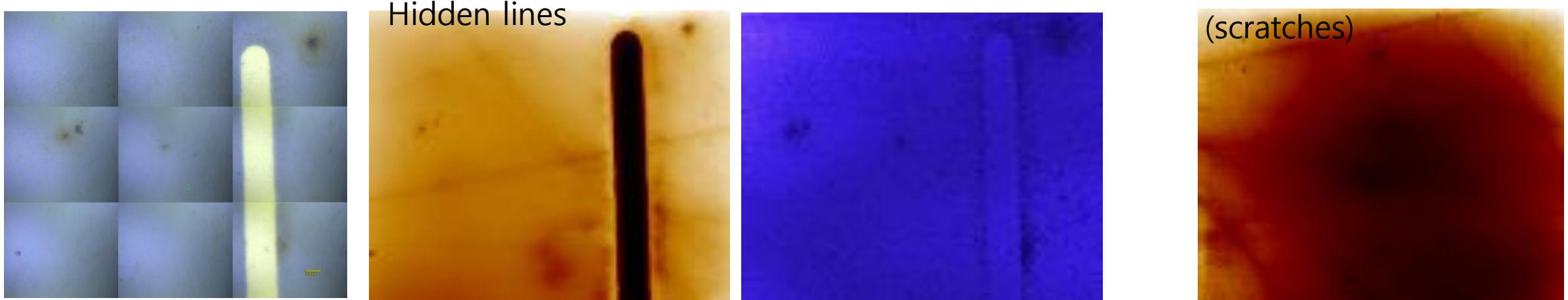
Local illumination measurement Using PhotoCurrent microscope



Ultra large area scanning with stability

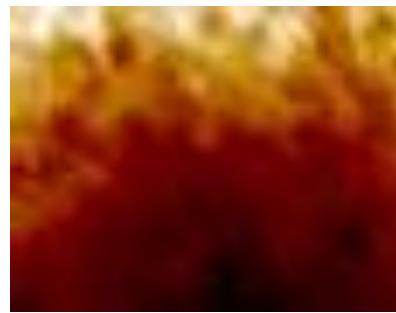
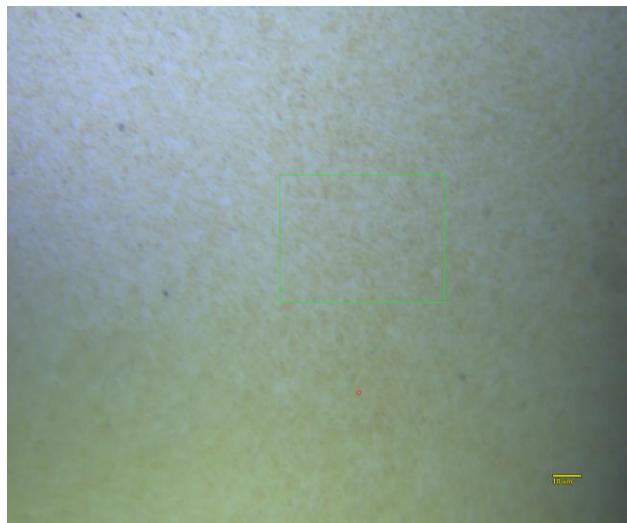


- MXene based solar cell with busbar electrodes
- 9 camera images are patched showing wide area: 600 um x 450 um



Failure analysis: Degradation by Photon irradiation

- MXene solar cell (**thin layer** diluted with 4ml DI water)



1st image

56 x 44 um



2nd image

56 x 44 um



3rd image
(30min later)

50 x 38 um



4th image
(30min later)

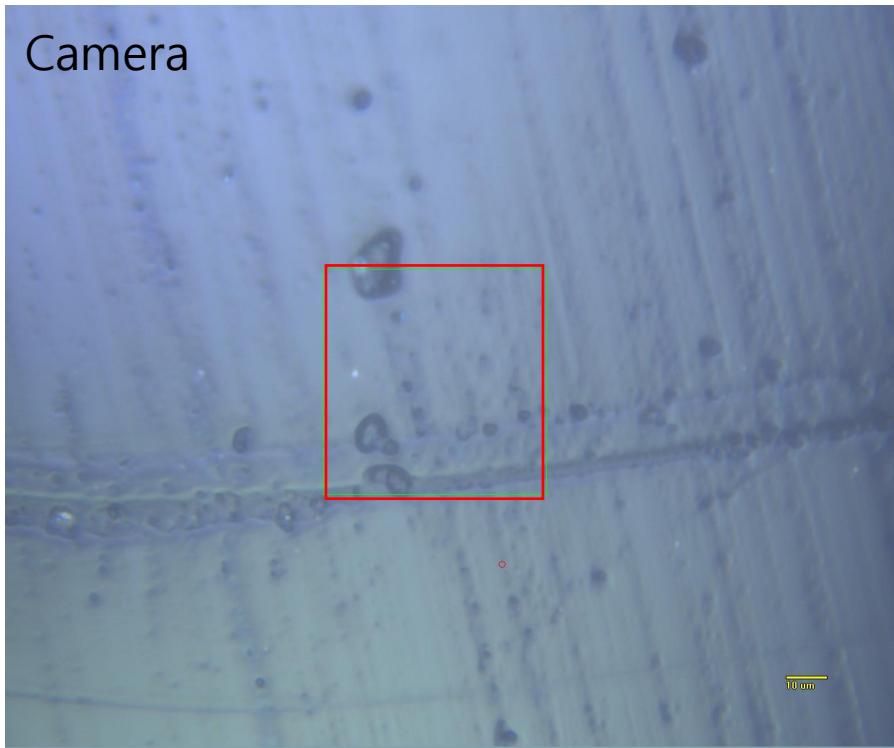
50 x 38 um



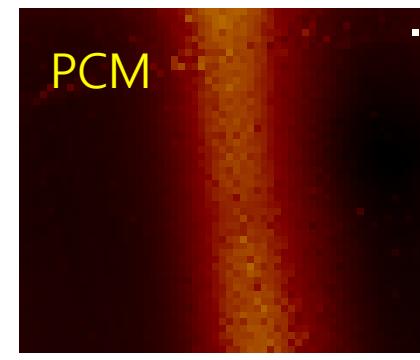
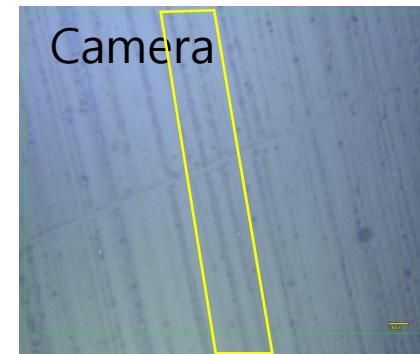
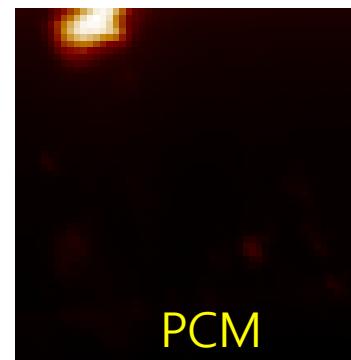
5th image
(30min later)

50 x 38 um

Failure analysis: defect on Si solar cell



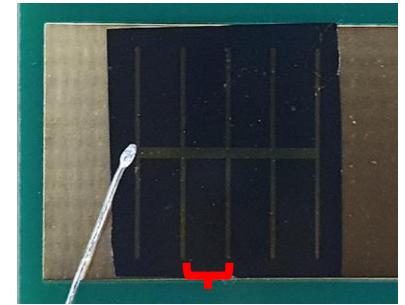
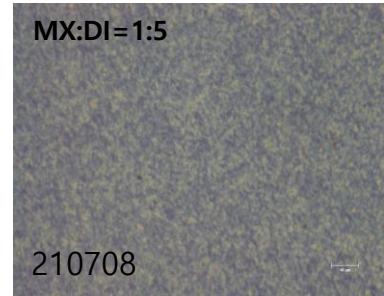
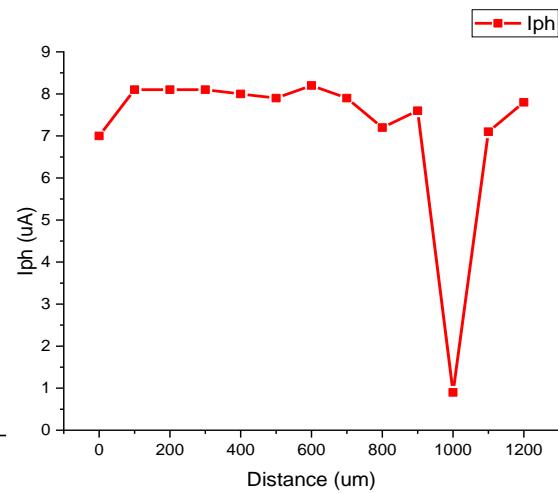
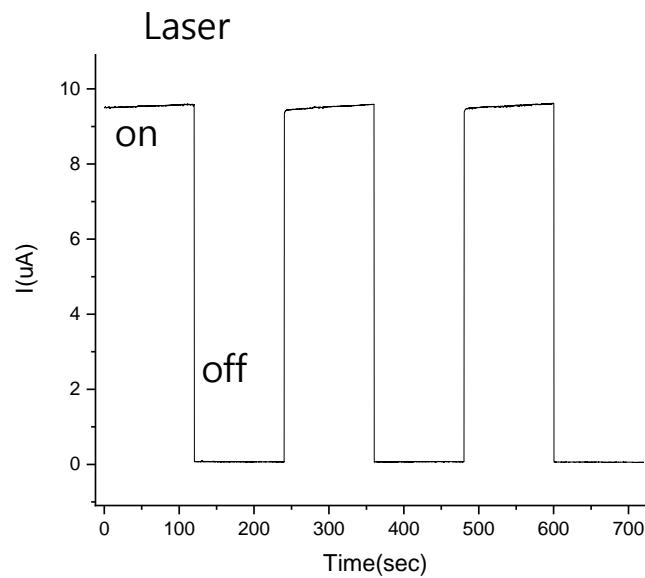
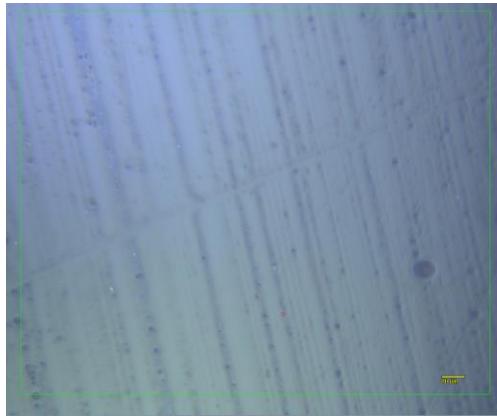
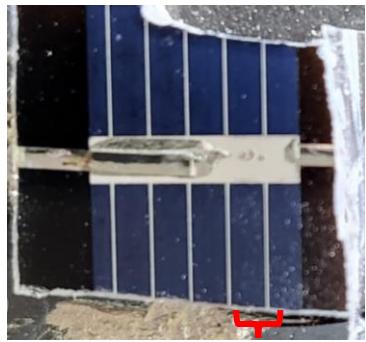
defect causes low photocurrent



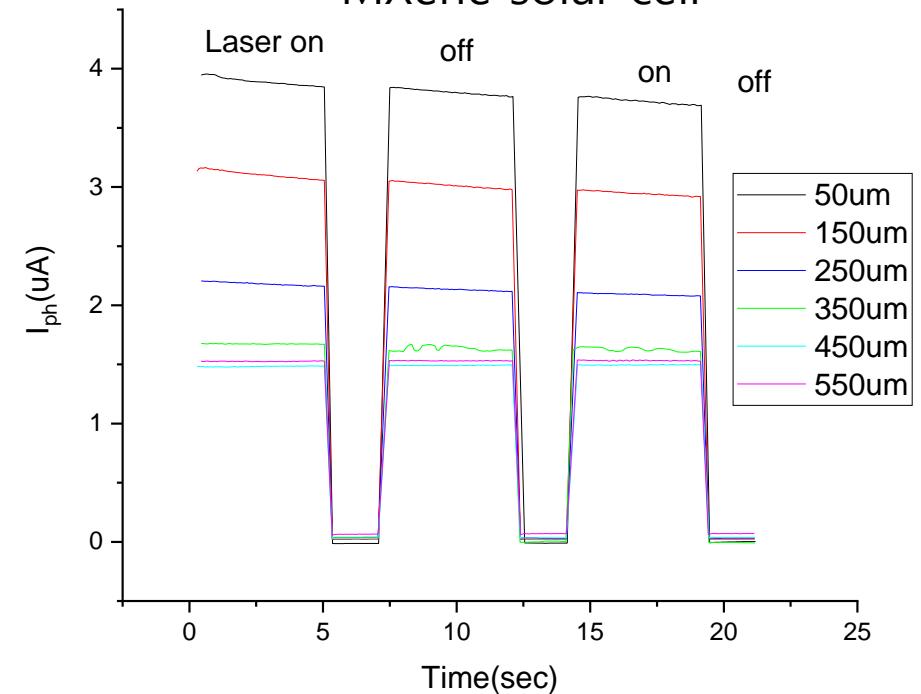
Hidden Electrode
located below

Degradation by Photon irradiation (Si vs MXene)

Si solar cell

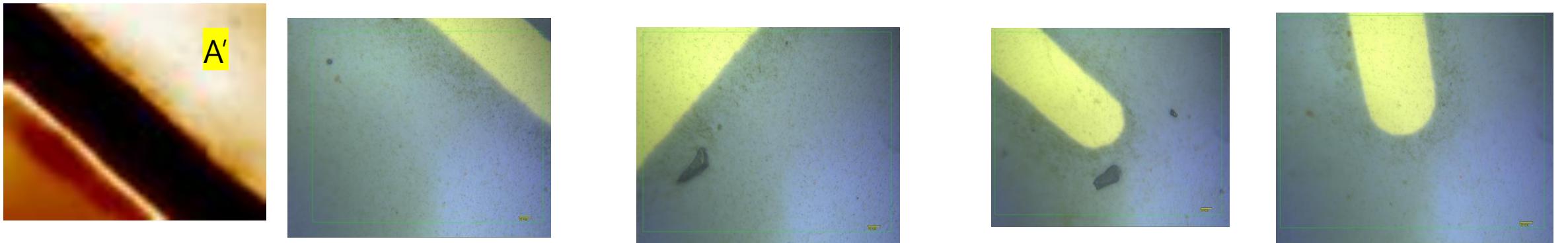
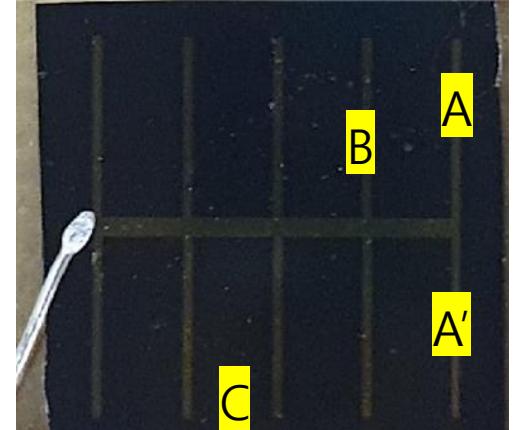


MXene solar cell

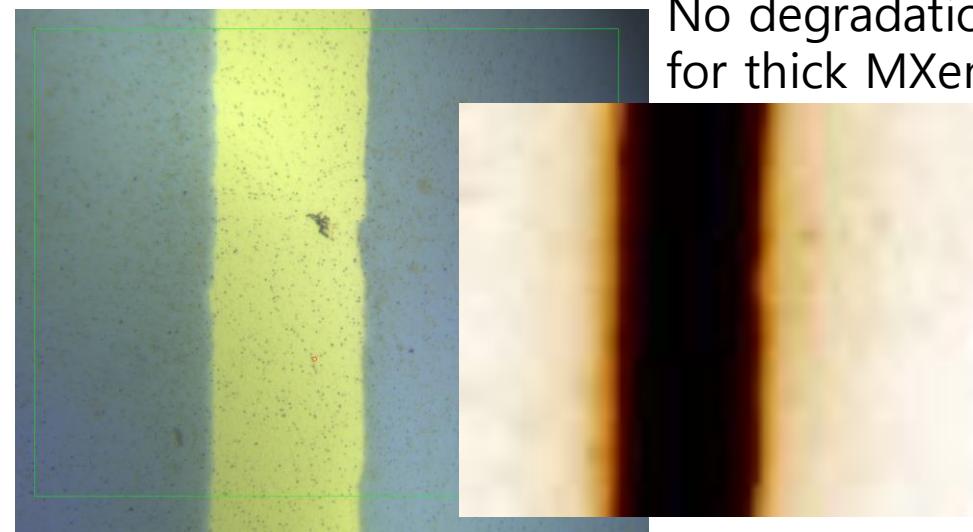
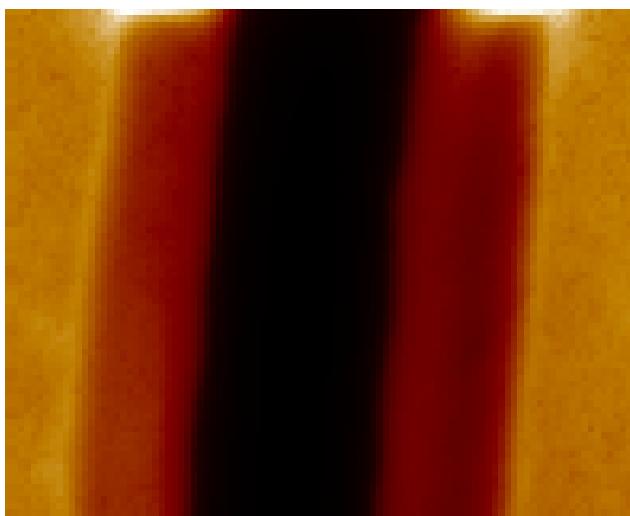
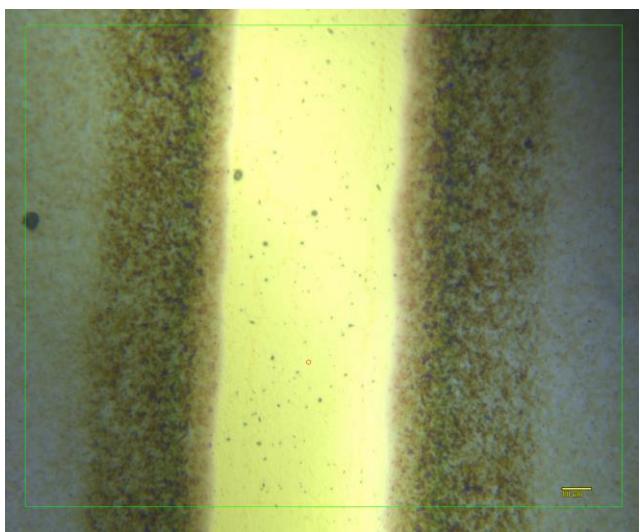
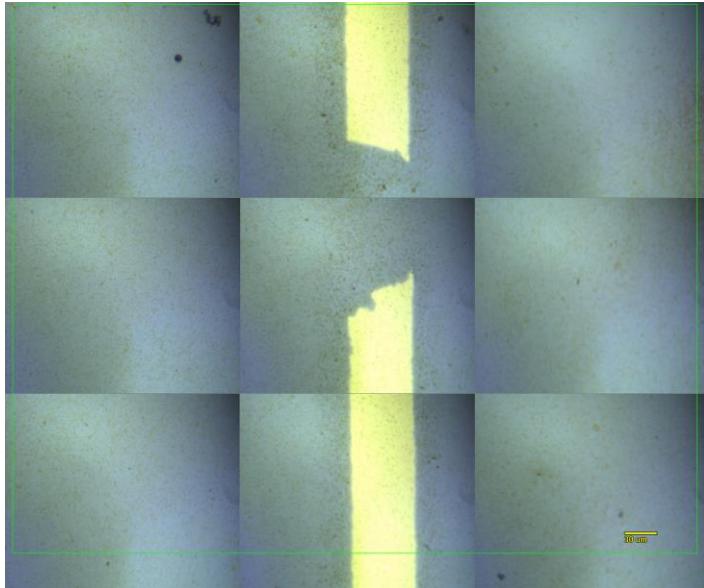


Photocurrent near electrodes

- For **thin MXene** layer high photocurrent density degrades MXene
- Serious degradation at narrow current path

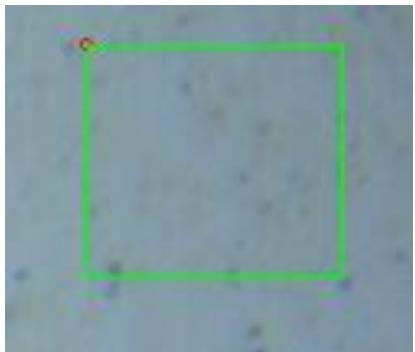
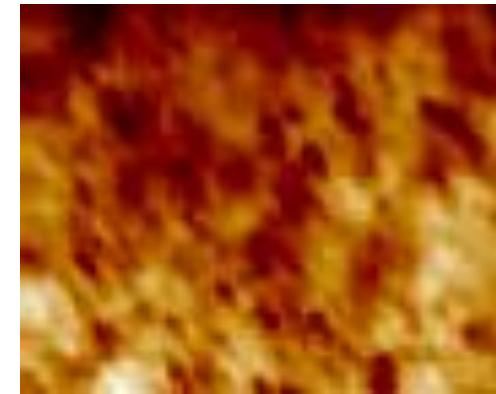
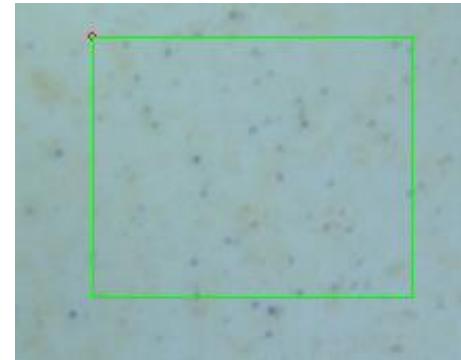
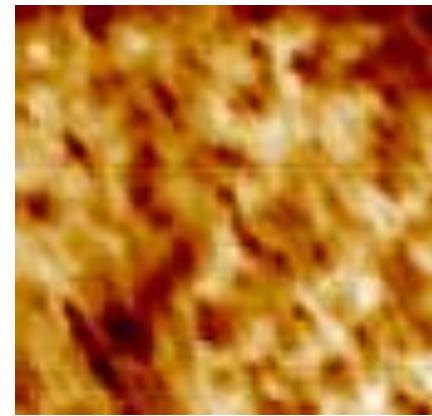
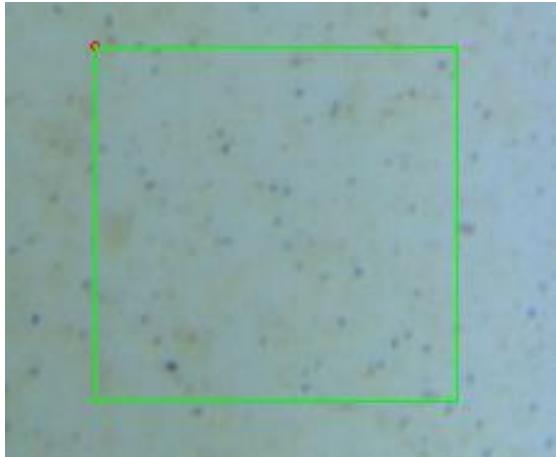


Current Profiling from asymmetric electrodes

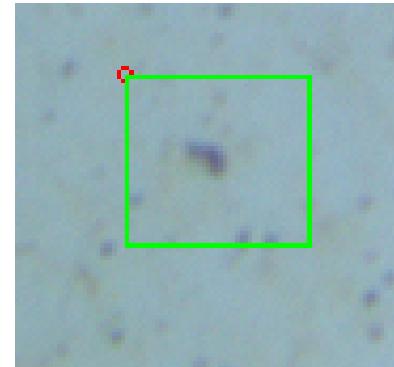


No degradation
for thick MXene

High resolution photocurrent map images (MXene solar cells)



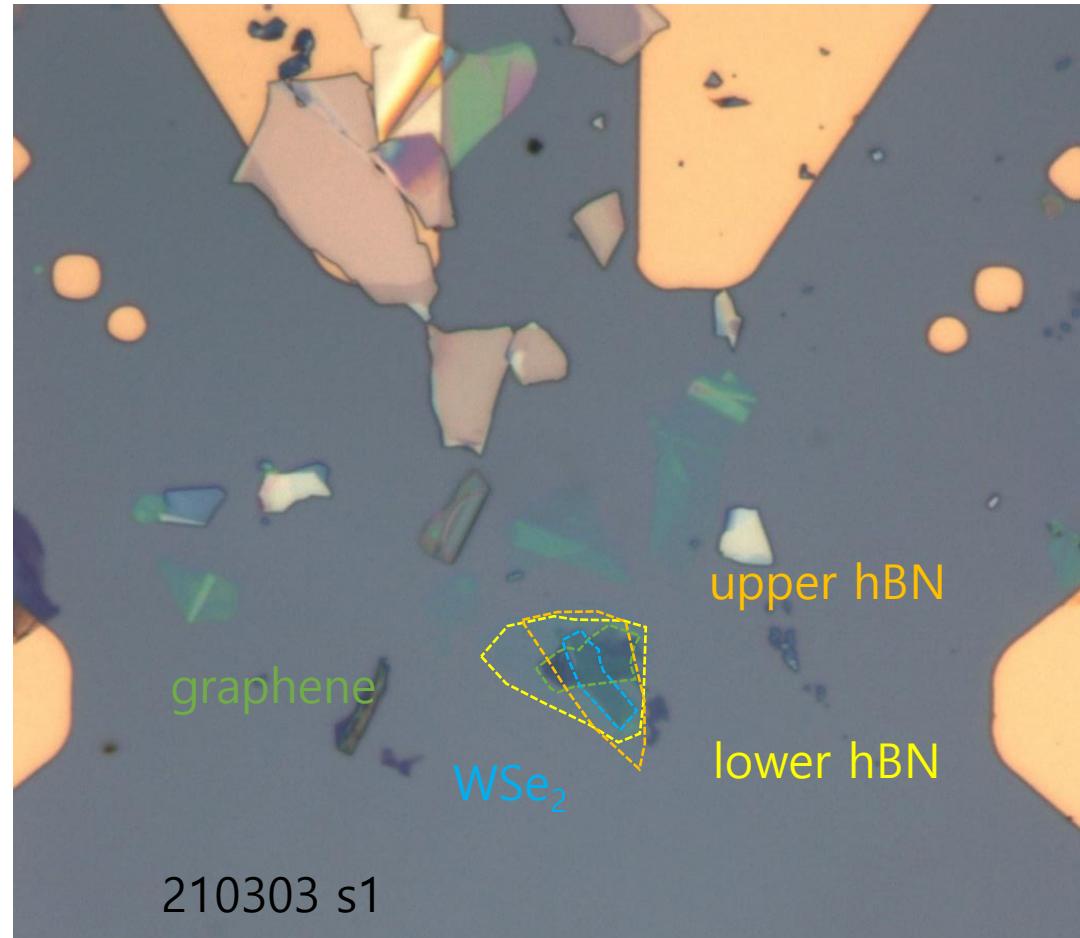
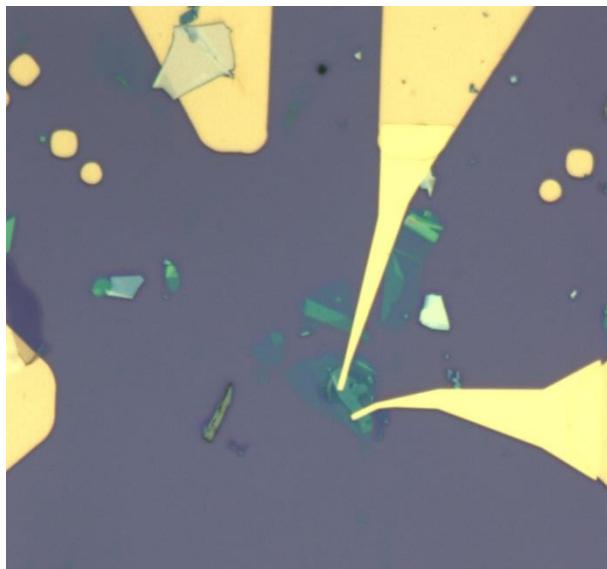
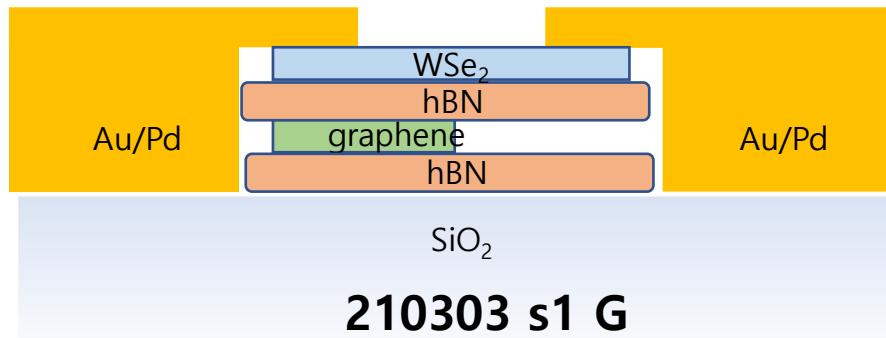
13 x 12 μm^2



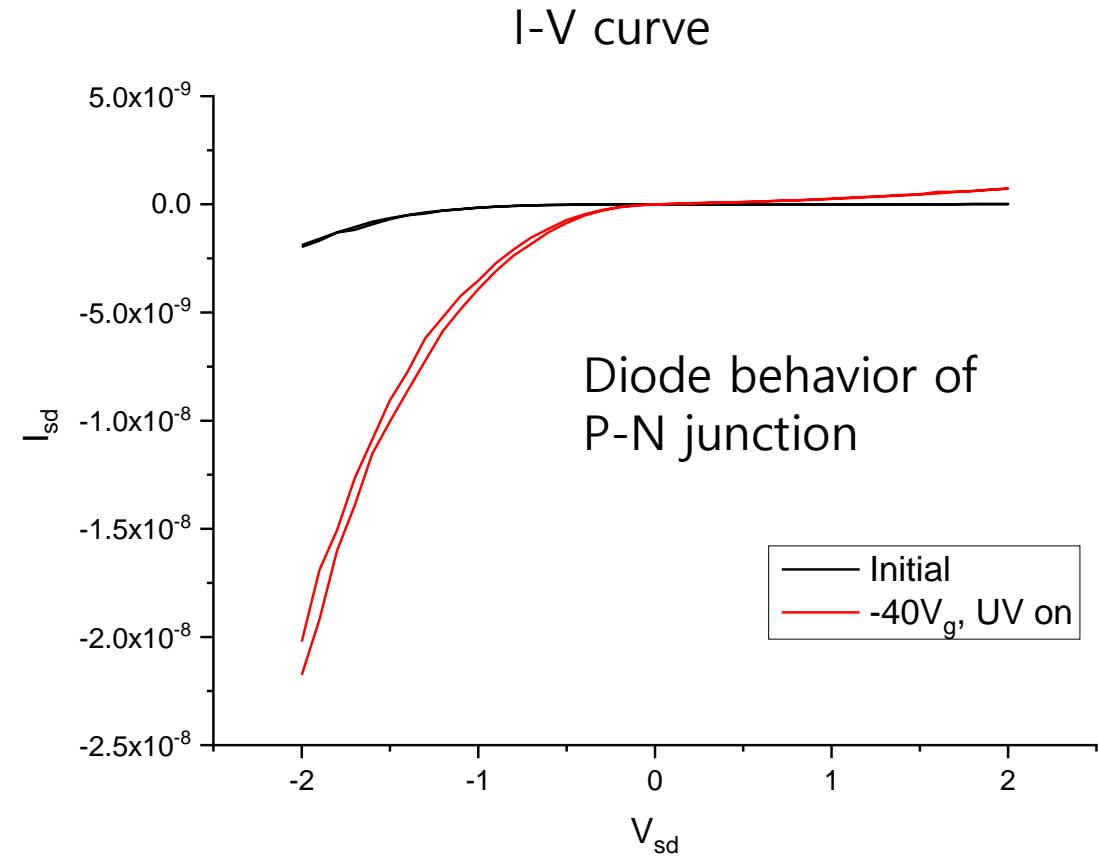
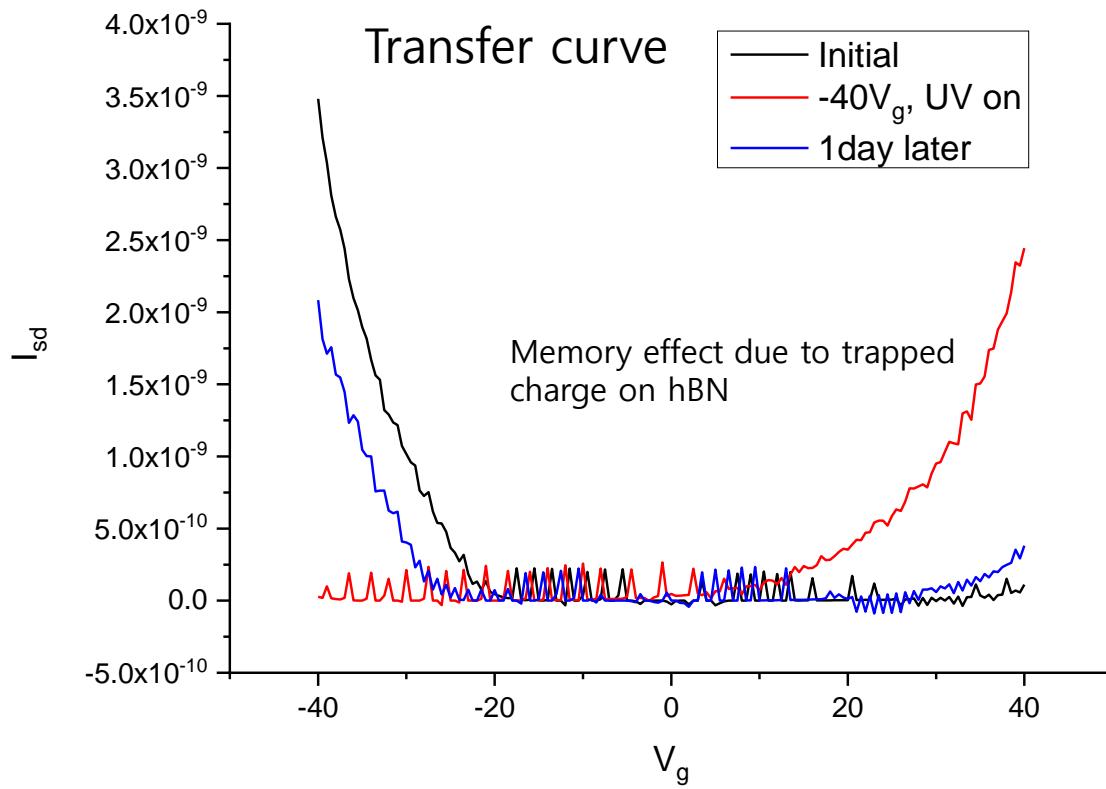
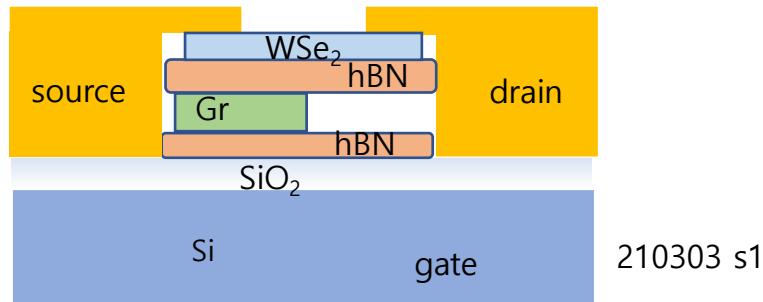
10 x 10 μm^2

2D materials based nano device

- Homo P-N junction with semi-floating gate device

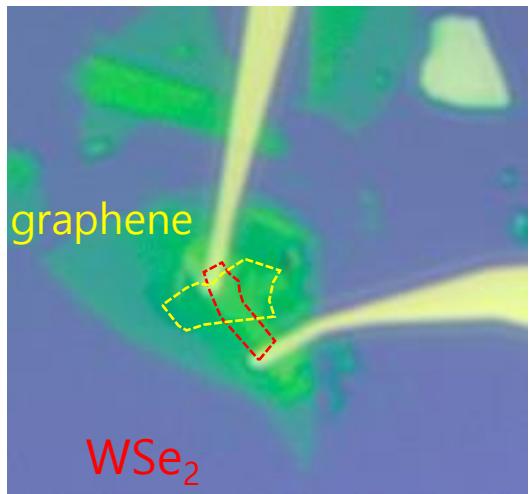


Transport measurement of P-N homojunction device

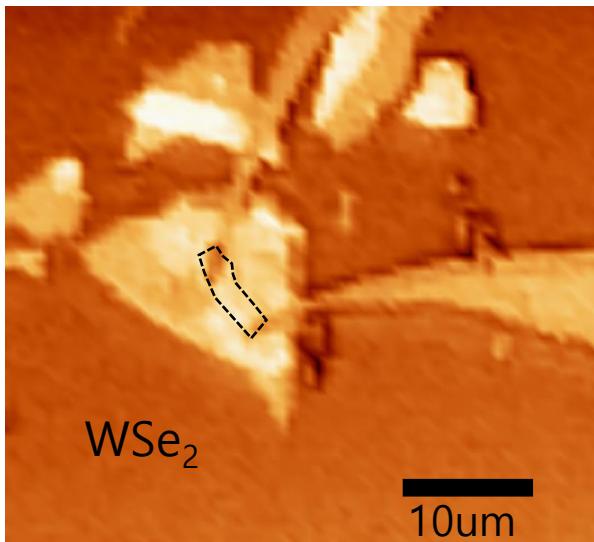


Photocurrent images of Nano device

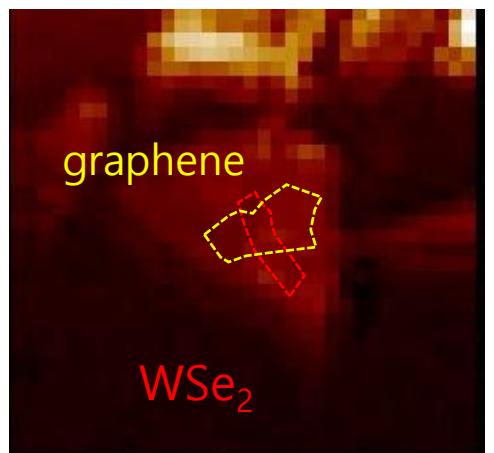
210303 s1 semi-floating(G)



width:47um height:42um



MoS₂/WSe₂/hBN Heterostructure



Reflective

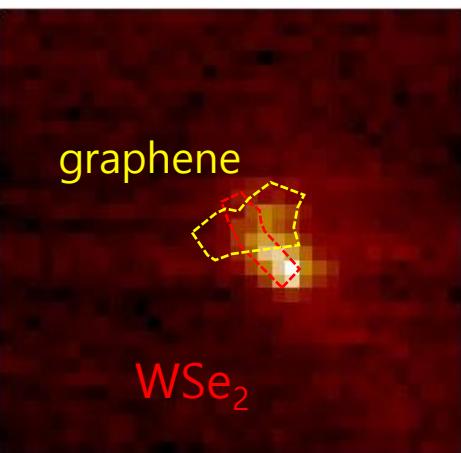
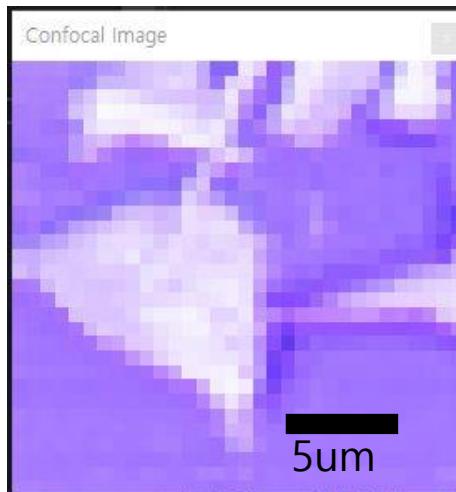


Photo Current
bias 0.5v

Reflective image



Confocal image

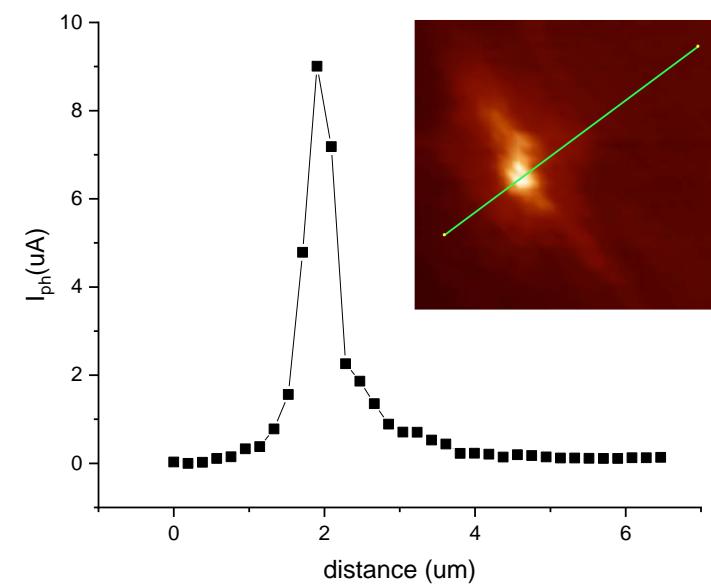


Photo Current

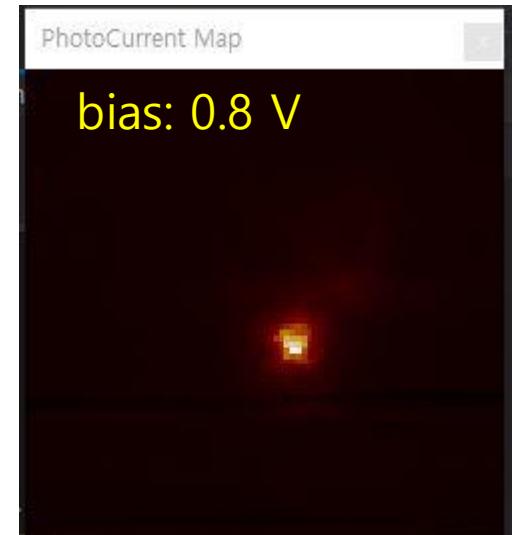
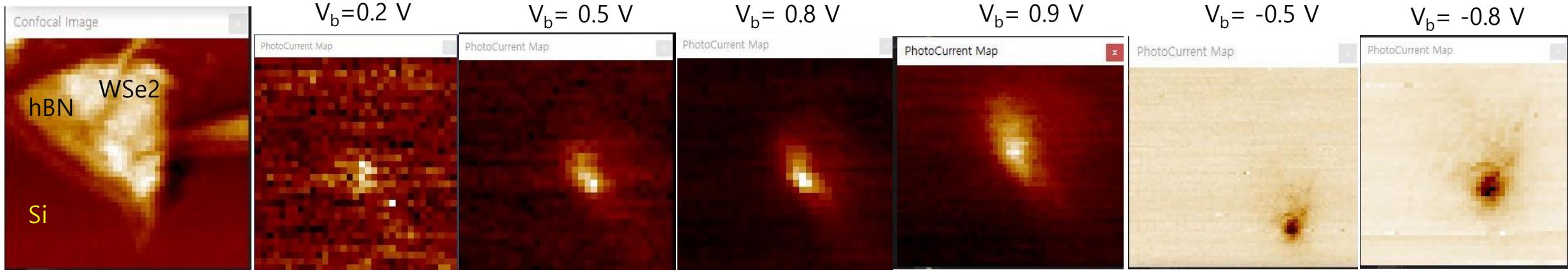
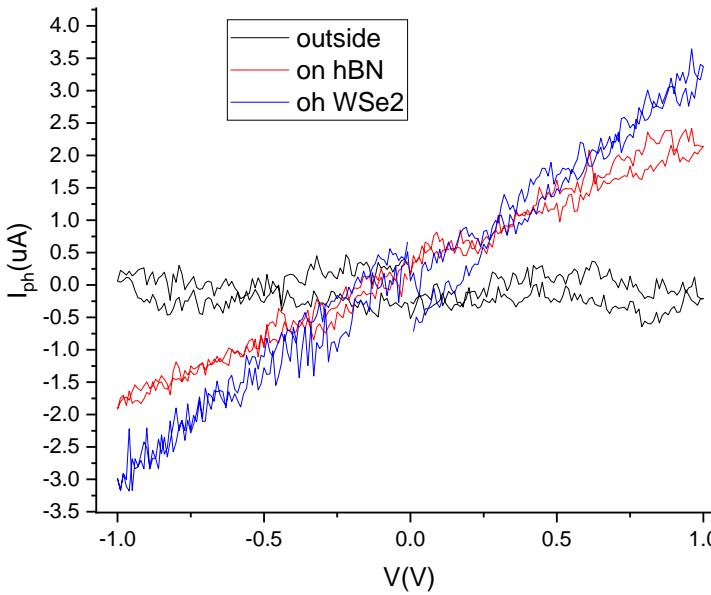


Photo Current

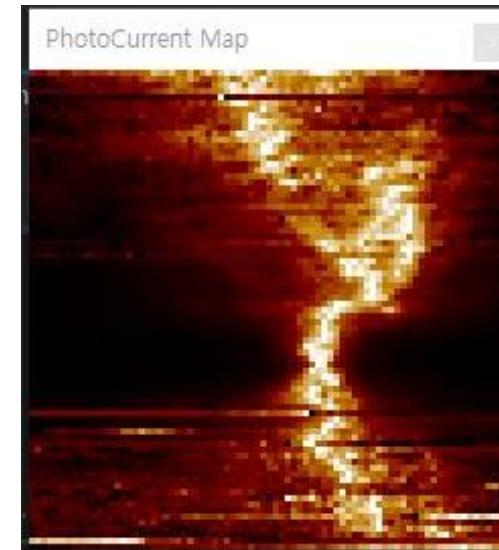
Images depending on bias voltages (V_b)



Confocal image



Line by line
plotting
 $V_b = 0.8 \text{ V}$



Current path
shifted after
repeated
measurements

Conclusion

- Scanning Photocurrent microscope can be utilized for analyzing photoelectric devices like solar cell, P-N diode, nano device, etc.
- Large scale uniformity test was demonstrated for MXene base solar cell device.
- Nano scale P-N homo junction device was analyzed with SPCM